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First Named Inventor	Munehiro TADA
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Attorney Docket Number	Q91732

**U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Document Number		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document
		Number	Kind Code <sup>2</sup> (if known)		
		US 2003/0001282	A1	01-02-2003	Herman Meynen
		US			
		US			
		US			
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		US			

**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document			Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Translation <sup>6</sup>
		Country Code <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)			
		JP	2000-183166	A	06-30-2000	NEC CORP.	
		WO	2001/054190	A1	07-26-2001	ADVANCED MICRO DEVICES	
		WO	2002/058134	A1	07-25-2002	STMICROELECTRONICS S.A.	
		JP	2002-83870	A	03-22-2002	TOKYO ELECTRON LTD.	
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		JP	2004-200203	A	07-15-2004	SEMICONDUCTOR LEADING, et al.	
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		JP	2003-347403	A	12-05-2003	FUJITSU LTD.	

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city, and/or country where published.	Translation <sup>6</sup>
		Tada, M., et al. "BARRIER-METAL-FREE (BMF), Cu DUAL-DAMASCENE INTERCONNECTS WITH Cu-epi-CONTACTS BURIED IN ANTI-DIFFUSIVE, LOW-k ORGANIC FILM," 2001 Symposium on VLSI Technology, June 12, 2001, pages 13-14.	
		Tada, M., et al. "A 65nm-NODE Cu INTERCONNECT TECHNOLOGY USING POROUS SiOCH FILM (K=2.5) COVERED WITH ULTRA-THIN, LOW-k PORE SEAL (k=2.7), International Electron Devices Meeting 2003 Technical Digest, December 8-10, 2003, pages 35.2.1 to 35.2.4.	

Examiner Signature

Date Considered

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